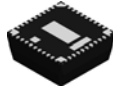


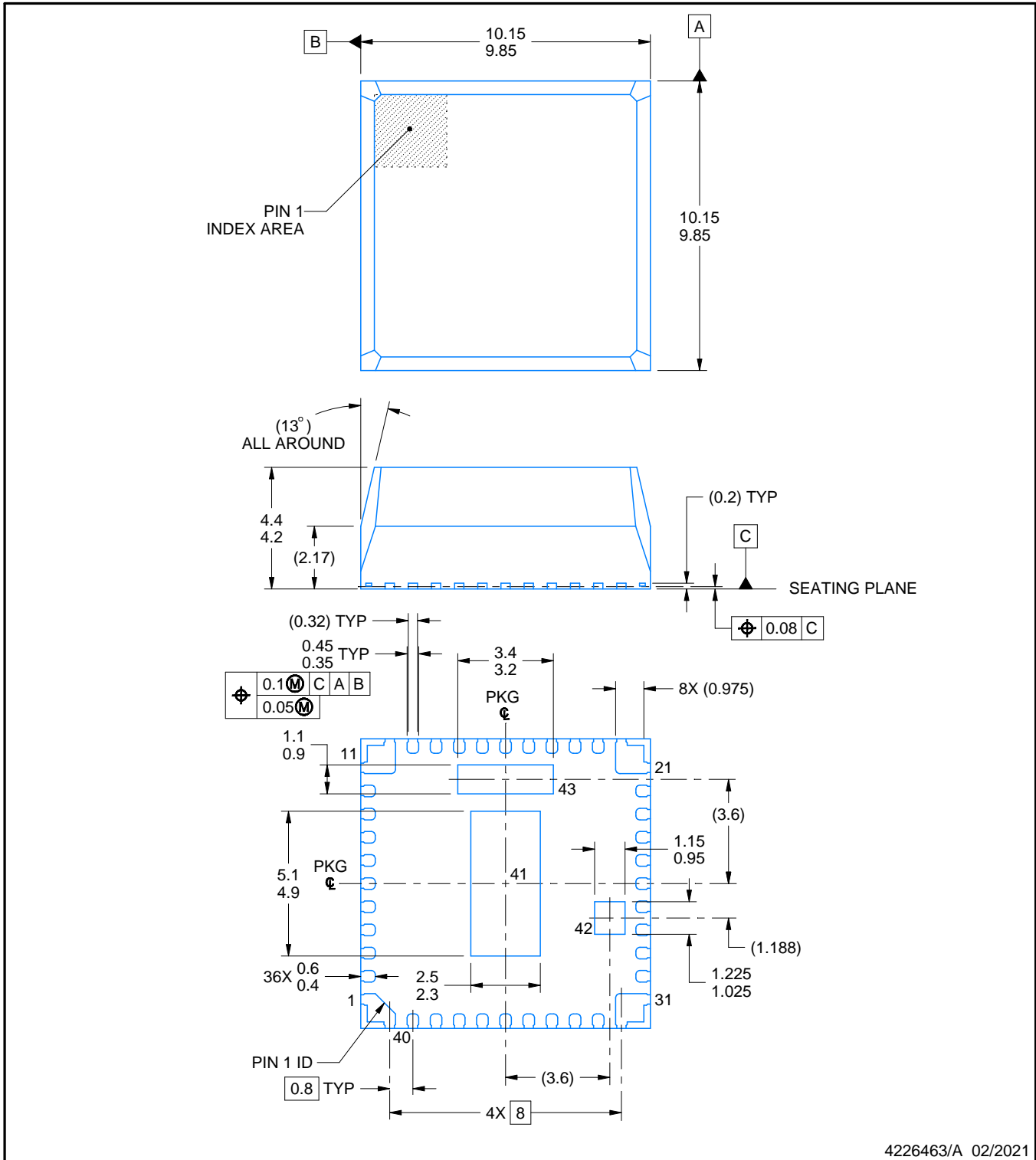
RVQ0043A



PACKAGE OUTLINE

B3QFN - 4.4mm max height

PLASTIC QUAD FLATPACK - NO LEAD



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NOTES:

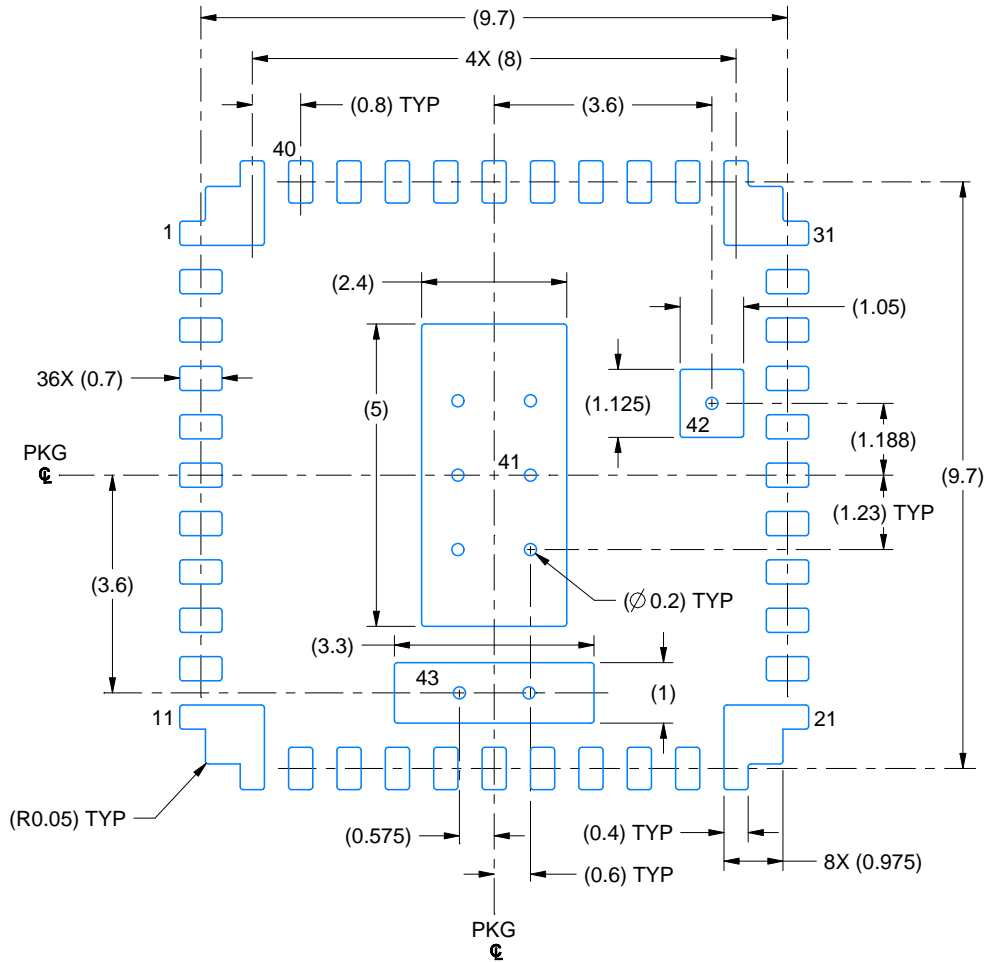
1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. The package thermal pads must be soldered to the printed circuit board for optimal thermal and mechanical performance.

# EXAMPLE BOARD LAYOUT

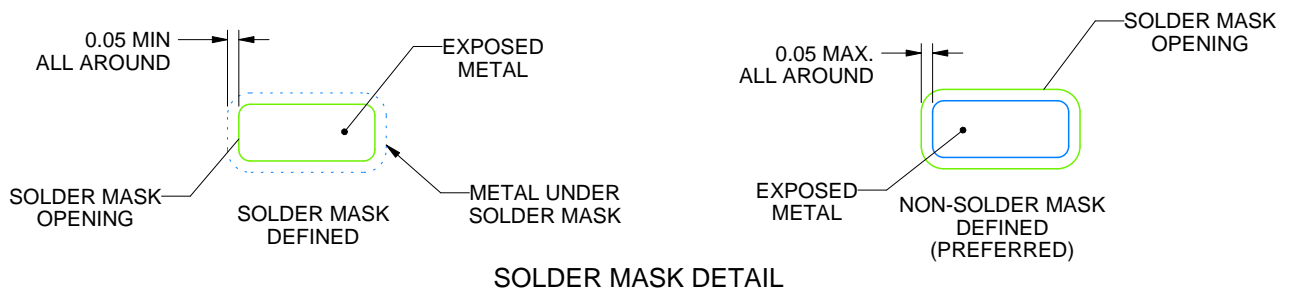
RVQ0043A

B3QFN - 4.4mm max height

PLASTIC QUAD FLATPACK - NO LEAD



LAND PATTERN EXAMPLE  
EXPOSED METAL SHOWN  
SCALE:8X



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NOTES: (continued)

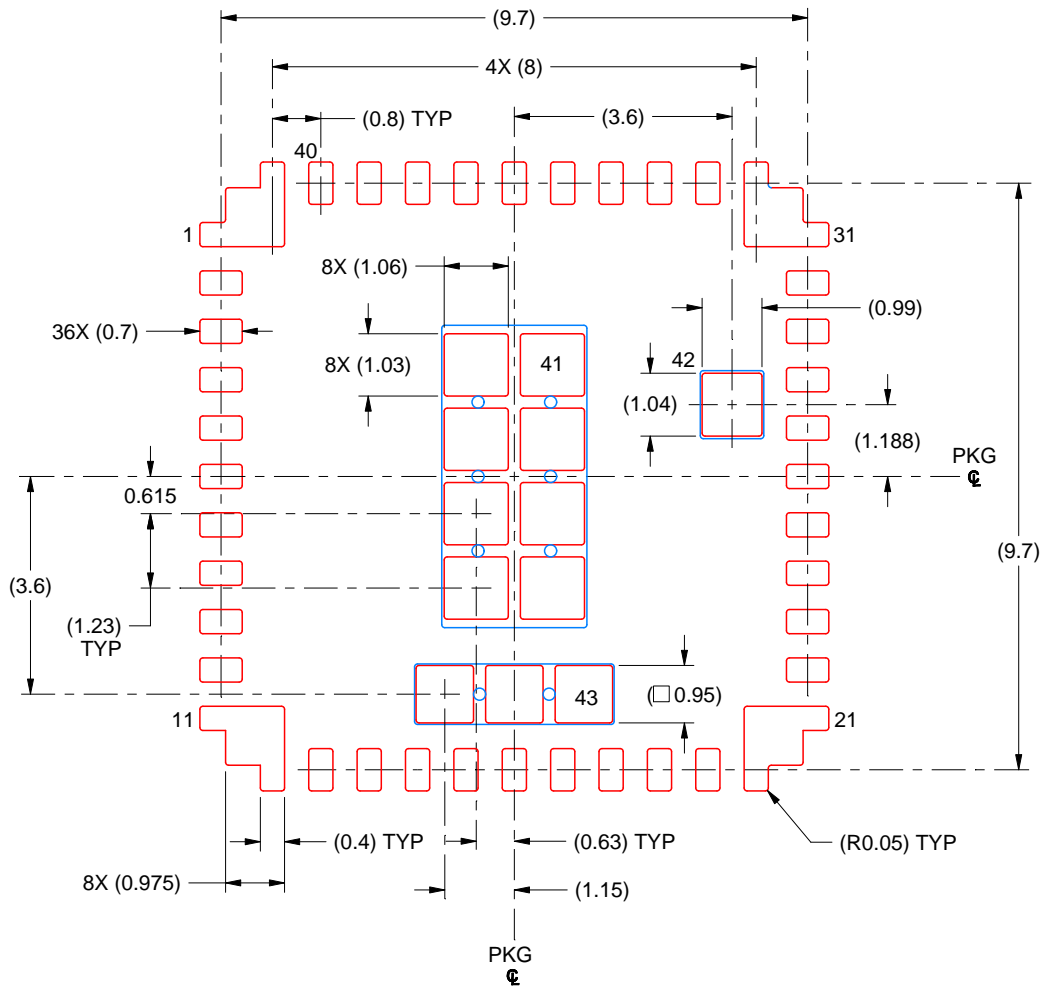
4. This package designed to be soldered to a thermal pads on the board. For more information, see Texas Instruments literature number SLUA271 ([www.ti.com/lit/slue271](http://www.ti.com/lit/slue271)).
5. Vias are optional depending on application, refer to device data sheet. If any vias are implemented, refer to their locations shown on this view. It is recommended that vias under paste be filled, plugged or tented.

# EXAMPLE STENCIL DESIGN

RVQ0043A

B3QFN - 4.4mm max height

PLASTIC QUAD FLATPACK - NO LEAD



**SOLDER PASTE EXAMPLE**  
 BASED ON 0.1 mm STENCIL THICKNESS

EXPOSED PAD 41:  
 73% PRINTED SOLDER COVERAGE BY AREA UNDER PACKAGE

EXPOSED PAD 42:  
 87% PRINTED SOLDER COVERAGE BY AREA UNDER PACKAGE

EXPOSED PAD 43:  
 82% PRINTED SOLDER COVERAGE BY AREA UNDER PACKAGE  
 SCALE:8X

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NOTES: (continued)

6. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.

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